

IN THE SPECIFICATION

Please replace Paragraph [0009] on Page 5 of the specification with the following paragraph:

-- [0009] Both the electroless plating waste line 16 and the stabilizing chemical line 18 extend through a wall of the external container 12, and have ends that are located above the internal container 14. Liquid, or other particular particulate matter, which flows through the lines 16 and 18 is dispensed through the ends of the lines 16 and 18 into the internal container 14. The electroless plating waste line 16 is connected to an electroless plating tank through a valve. (The line 16 may alternatively be connected through a valve to a waste holding tank.) The stabilizing chemical line 18 is connected through a valve to a tank containing a stabilizing chemical or chemicals. (The stabilizing chemical line 18 may alternatively be connected to a bulk chemical delivery system.) --

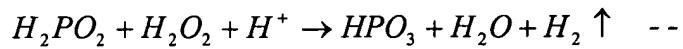
Please replace Paragraph [0017] on Pages 7-8 of the specification with the following paragraph:

-- [0017] The valve connecting the electroless plating waste line 16 to the electroless plating bath is opened. An electroless plating waste flows from the electroless plating bath through the electroless plating waste line 16, and dispenses through its end into the internal container 14 (Step 202). The electroless plating waste may, for example, be a cobalt electroless plating waste, a

nickel electroless plating waste which is the same as the cobalt waste, or a copper electroless plating waste. A cobalt electroless plating waste may, for example, include cobalt, citric acid, NH₄Cl, tetramethyl ammonium hydroxide (TMAH), with ~~dimethyle~~ dimethyl amine borane (DMAB) complex as a reducing agent. A copper electroless plating waste may, for example, include copper, ethylene diamine tetraacetic acid (EDTA), TMAH, and either a formaldehyde or glyoxylic acid as a reducing agent. --

Please replace Paragraph [0025] on Page 12 of the specification with the following paragraph:

[0001] -- [0025] The ability for the reducing agent to reduce the metal can be decreased by changing the anodic potential of the reducing agent toward a cathodic potential of the metal, or by changing the cathodic potential of the metal toward the anodic potential of the reducing agent. For example, the copper electroless plating waste, including formaldehyde or glyoxylic acid as a reducing agent, can be admixed with H₂SO₄, HCl, HNO₃, etc., to reduce the pH of the electroless plating waste from between eleven and thirteen to between seven and eight, with a corresponding change in the anodic potential of the reducing agent toward a cathodic potential. A typical reaction of this kind can be represented by the following chemical reaction:



Please replace Paragraph [0029] on Page 14 of the specification with the following paragraph:

-- [0029] The ability of the reducing agent to reduce the metal may also be increased without adding any stabilizing chemicals to the electroless plating waste. A positive voltage can be applied to an anode to which the electroless plating waste is exposed. The reducing agent is oxidized by the anode. A cathode is also located in the waste to complete the circuit. Metal ions plate out over the cathode. To remove/dissolve the metal from the cathode, the potential over the anode and the cathode can be reversed so that the anode becomes the cathode and the cathode[[,]] becomes the anode. The potential can be reversed at a frequency of between one second to a few minutes. --